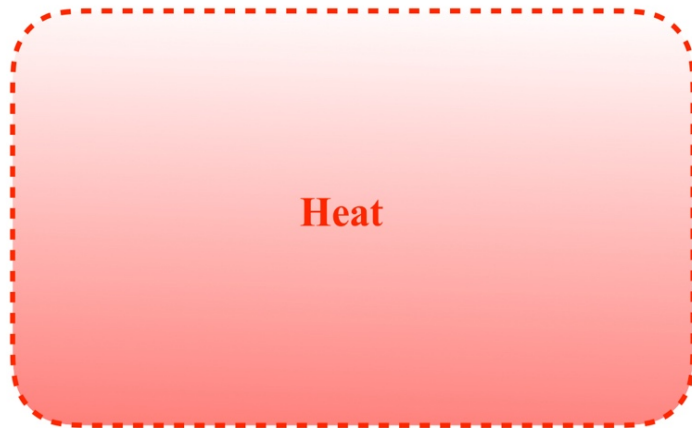
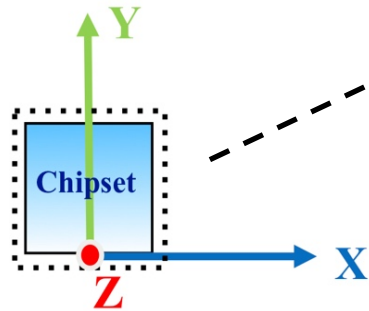
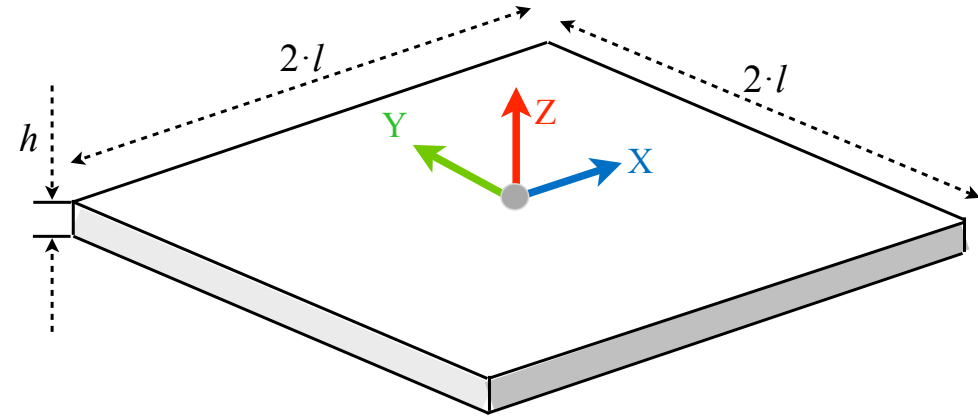


Thermal image of chip

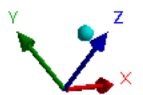
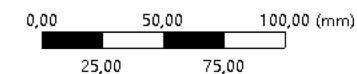
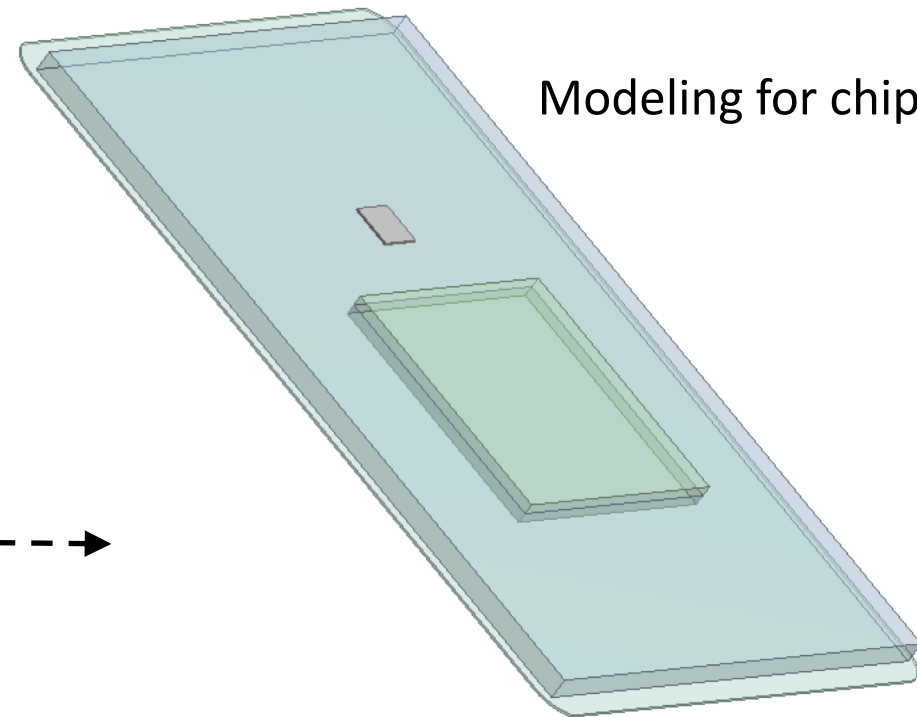


Schematic of smartphone thermal field

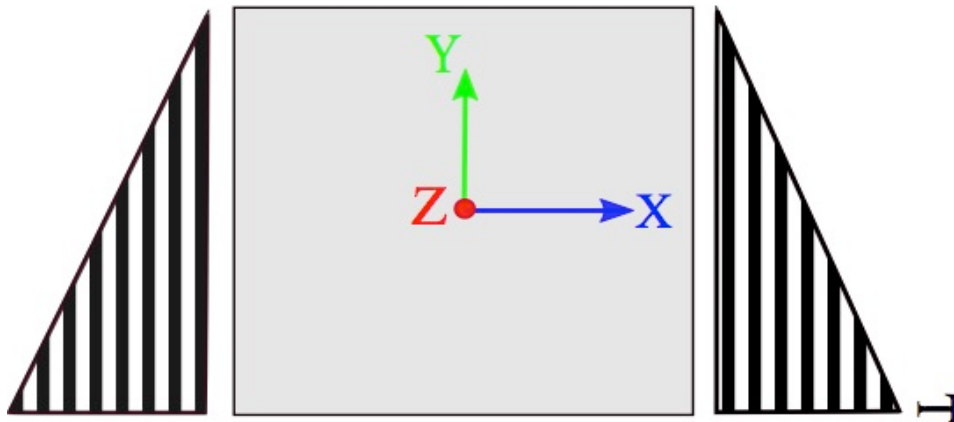
Modeling of chip



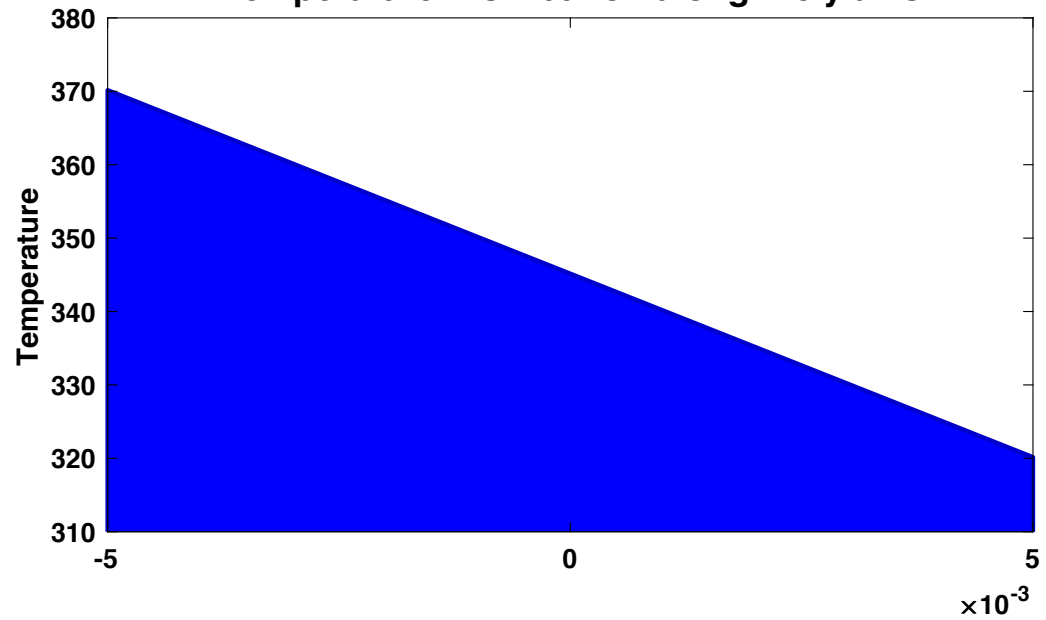
Modeling for chip simulation



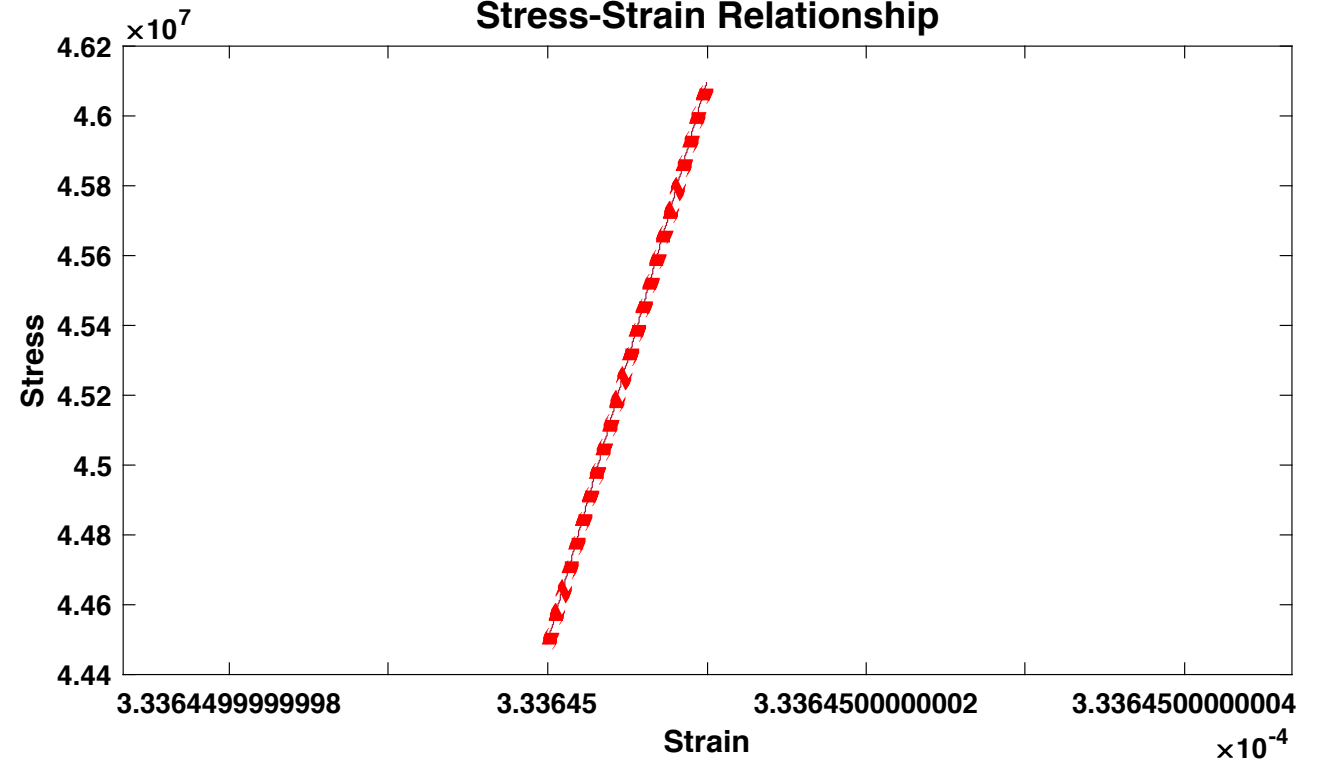
Temperature Distribution

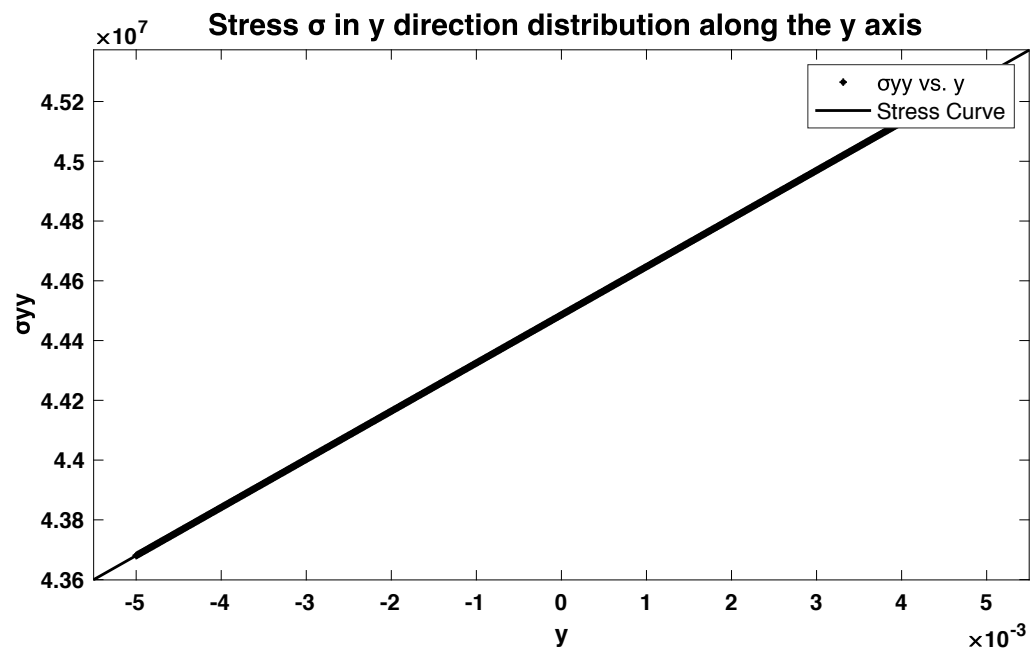
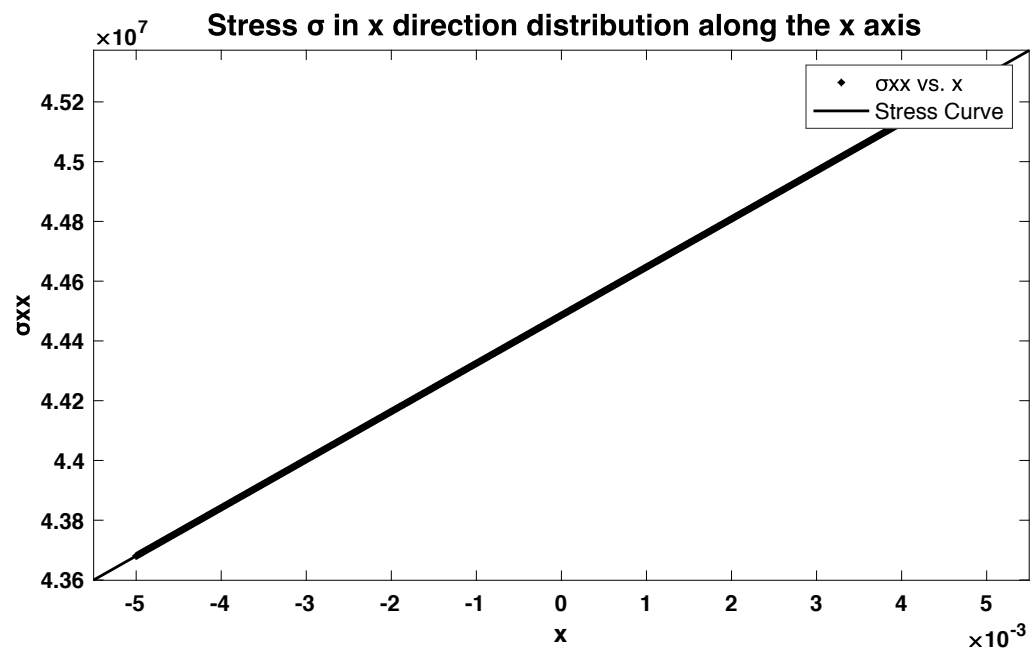


Temperature Distribution along the y axis

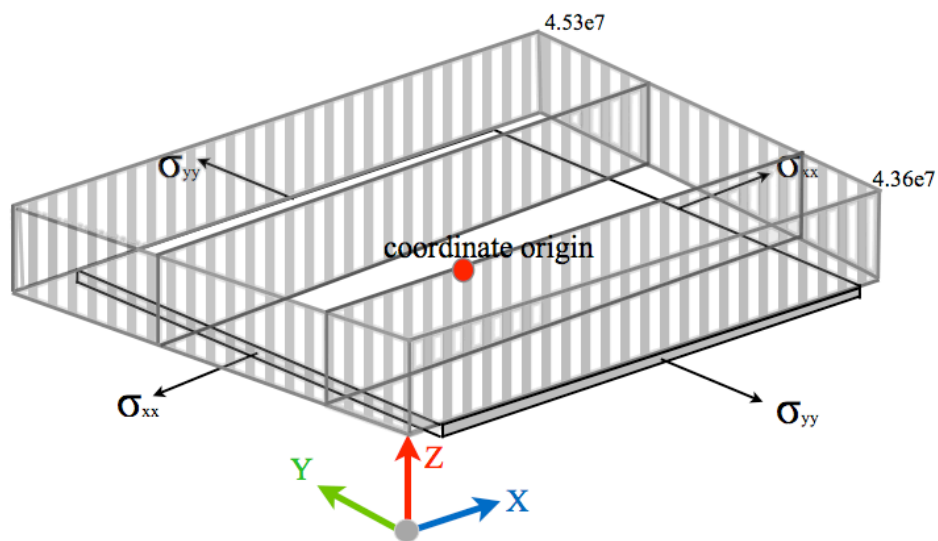


Stress-Strain Relationship

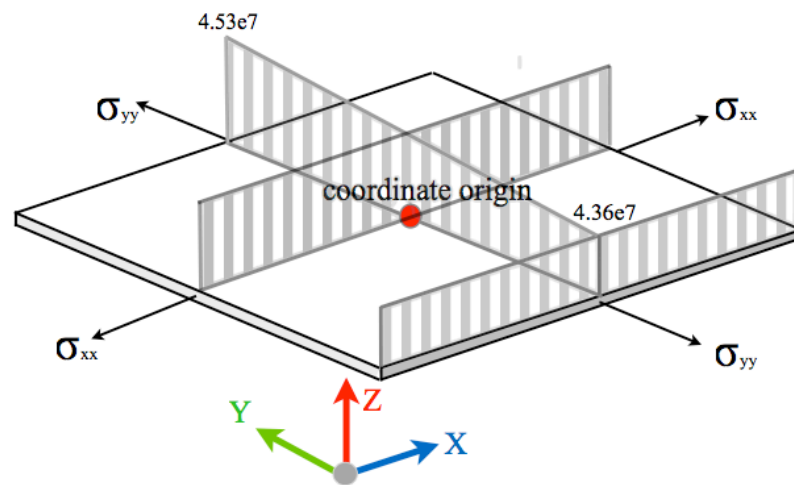


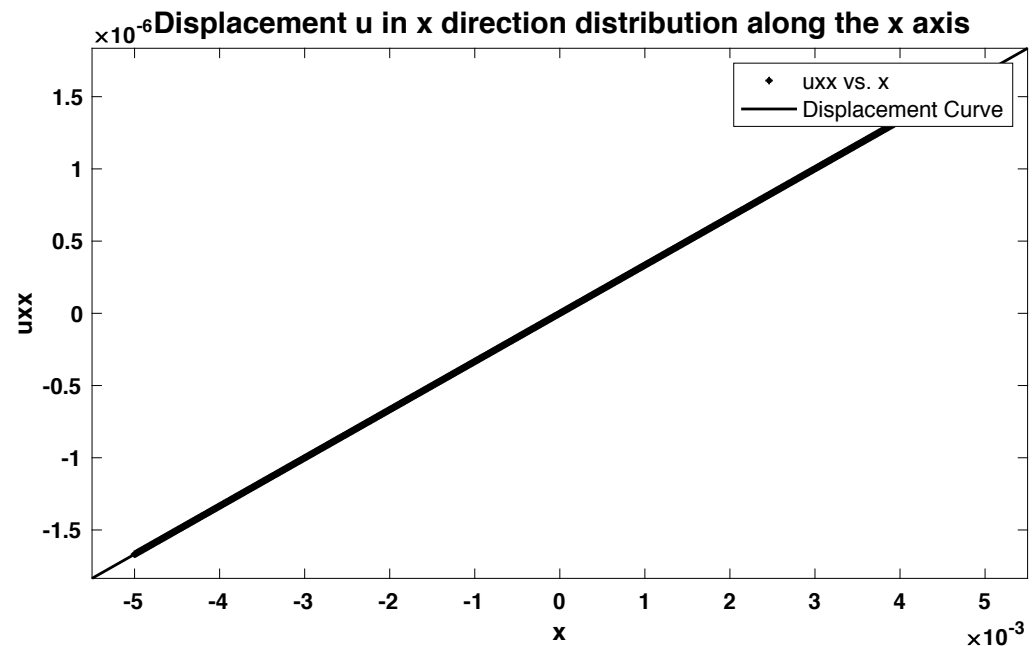


Stress σ_{xx} distribution along the chip

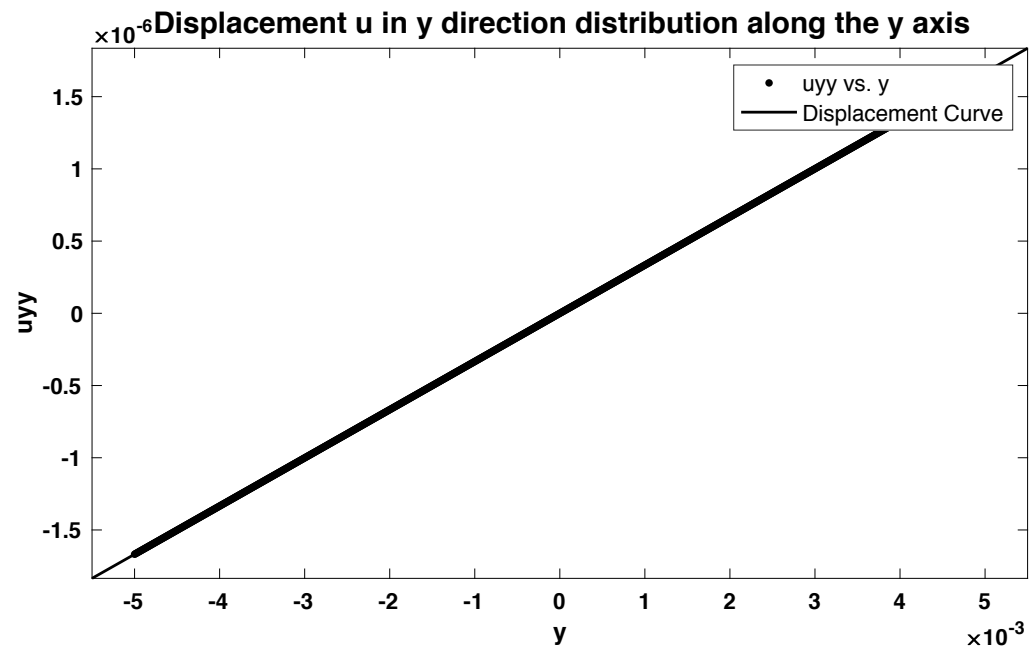
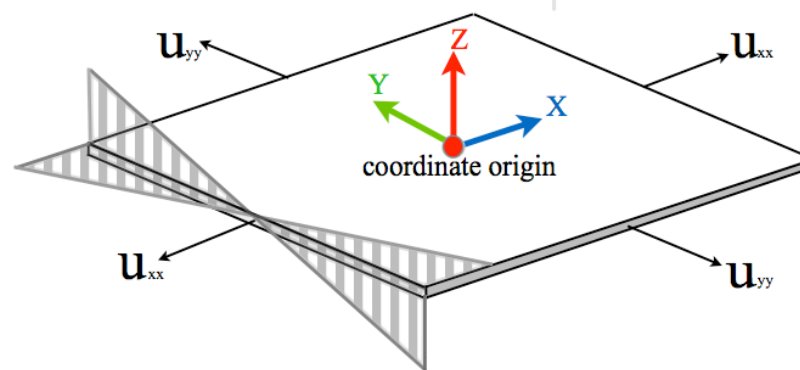


Stress σ_{yy} distribution along the chip

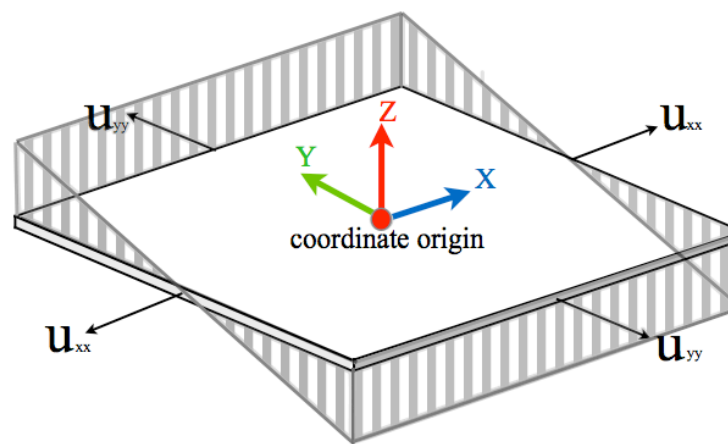




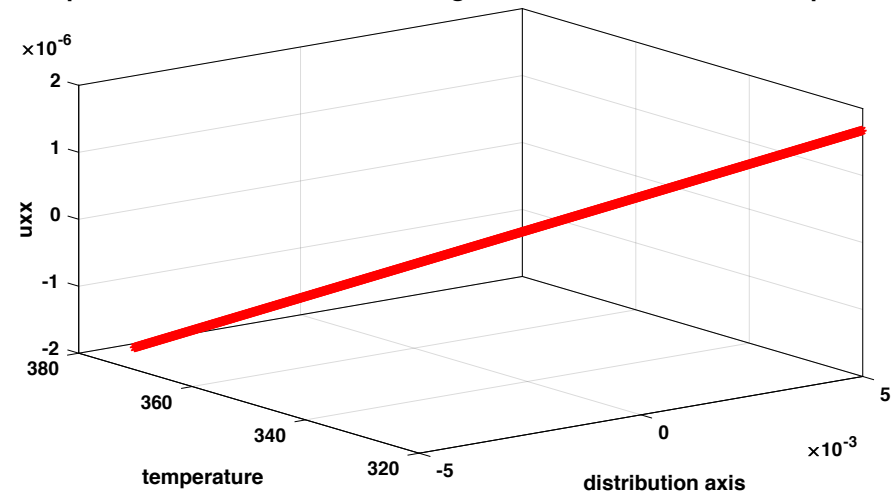
Displacement u_{xx} distribution along the chip



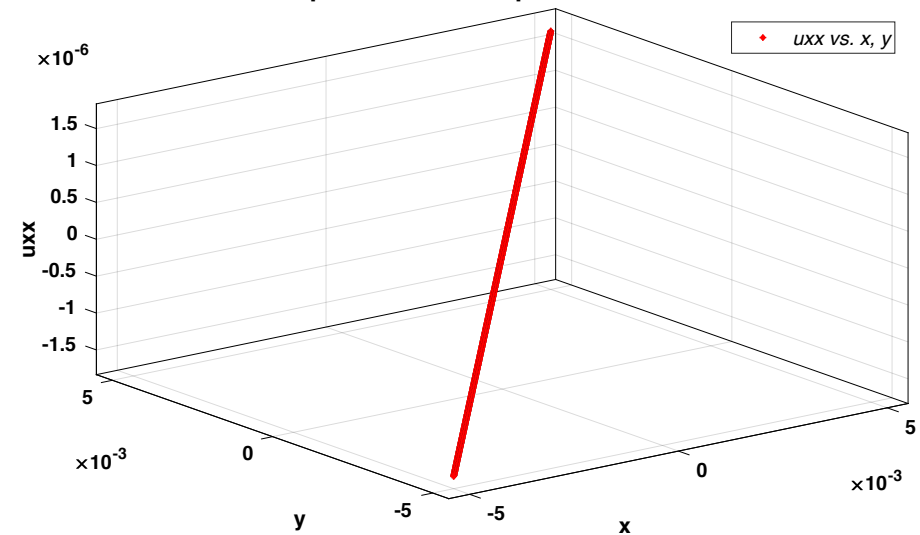
Displacement u_{yy} distribution along the chip



Displacement uxx distribution along the coordinate axis and temperature

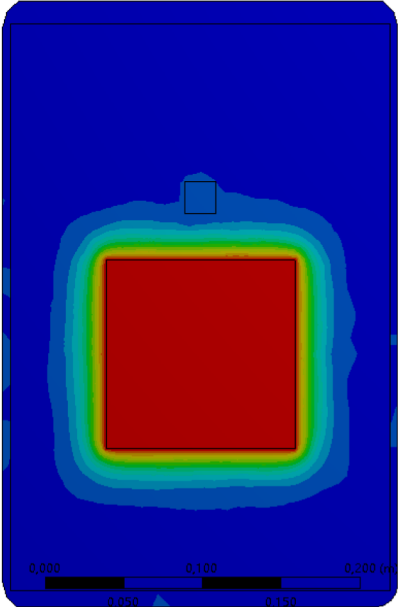


Displacement uxx spatial distribution



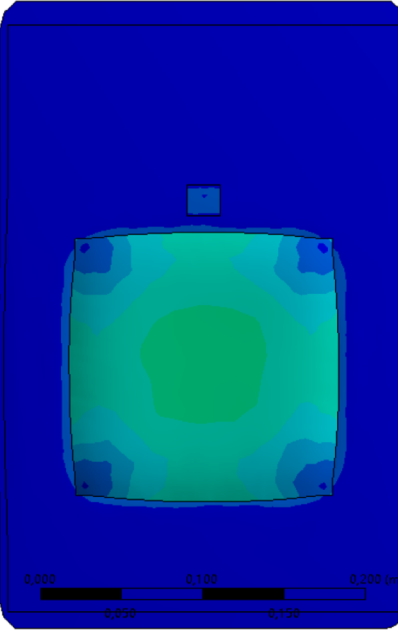
B: Steady-State Thermal

Temperature
Type: Temperature
Unit: °C
Time: 2
Custom Obsolete
8/1/2020 6:52 μμ
7,00215e1
7,00200e1 Max
6,41297e1
5,87337e1
5,37917e1
4,92655e1
4,51201e1
4,13236e1
3,78465e1
3,46620e1
3,17454e1
2,90743e1
2,66279e1
2,43873e1
2,23353e1
2,04560e1



C: Static Structural

Equivalent Stress
Type: Equivalent (von-Mises) Stress
Unit: Pa
Time: 1
8/1/2020 7:02 μμ
1,6014e8 Max
1,487e8
1,3727e8
1,2583e8
1,1439e8
1,0295e8
9,1512e7
8,0073e7
6,8634e7
5,7196e7
4,5757e7
3,4318e7
2,288e7
1,1441e7
2406,7 Min



C: Static Structural
Total Deformation
Type: Total Deformation
Unit: m
Time: 1
8/1/2020 7:02 μμ

5,5571e-5 Max
5,1602e-5
4,7632e-5
4,3663e-5
3,9694e-5
3,5724e-5
3,1755e-5
2,7786e-5
2,3816e-5
1,9847e-5
1,5877e-5
1,1908e-5
7,9387e-6
3,9694e-6
0 Min

